

AMENDMENTS TO THE CLAIMS

Claims 1-4 (Cancelled).

5. (New) A method of managing a plating liquid used in a plating apparatus, said method comprising:

sampling the plating liquid;

analyzing components of the sampled plating liquid using an automatic analyzing device;

and

based on results of said analyzing, replenishing the plating liquid with component replenishing liquids containing the components of the plating liquid, said replenishing comprising replenishing the plating liquid with component replenishing liquids each including:

a standard liquid; and

a plurality of solutions each including:

a basic liquid including copper sulfate and sulfuric acid; and

one of a plurality of different types of additives;

wherein the standard liquid includes the basic liquid, the plurality of different types of additives, and hydrochloric acid.

6. (New) The method of claim 5, wherein a total amount of the component replenishing liquids to be supplied to the plating liquid is substantially equal to a reduction of an amount of the plating liquid caused by plating substrates in the plating apparatus.

7. (New) The method of claim 5, wherein said replenishing is further based on a quantity of substrates plated by the plating apparatus, in addition to being based on the results of said analyzing.

8. (New) The method of claim 5, wherein said replenishing is further based on a quantity of electricity consumed due to plating substrates in the plating apparatus, in addition to being based on the results of said analyzing.
9. (New) The method of claim 5, further comprising changing a frequency of said sampling during an operation of the plating apparatus.
10. (New) The method of claim 5, wherein said replenishing is performed in a manner so as to maintain concentrations of the components of the plating liquid within a certain management range.